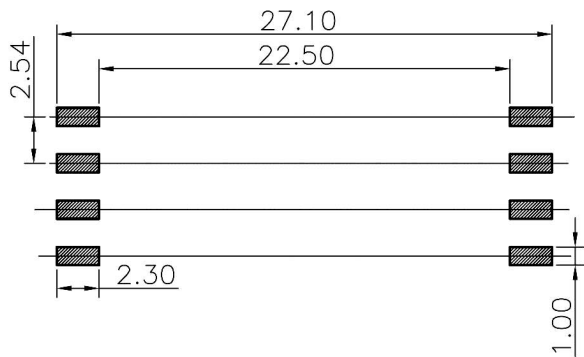


Specifications  
 Current Rating: 1Amp  
 Insulation Resistance: 1000MΩ Min.  
 Dielectric Withstanding: 250VAC  
 Contact Resistance: 100mΩ Max  
 Operating Temperature: -40°C to +85°C  
 Max Process Temp: 200°C for 20~30 sec.  
 (230°C for 10-15seconds)

Materials  
 Contact Material: Phosphor Bronze  
 Insulator Material: High Temperature Thermoplastic, UL 94V-0  
 LCP Or Equivalent material (Housing 1)  
 LCP Or Equivalent material (Housing 2)

Recommended P.C. Board Layout  
 (Tolerance: ±0.05)



RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准 HELEN	SCALE 比例 参考	TOLERANCE X'±5.0' X±0.30 .X'±3.0' X±0.25 .XX'±2.0' .XX±0.15 XXX'±1.0' XXX±0.10	PART NAME 品名 SIM CARD BLOCK TYPE HINGED COVER 8PIN SMT TYPE H=2.5mm SELECTIVE GOLD 30U" PLATING W/O SWITCH W/O LOCATING POST REEL PACKING BLACK COLOR INSULATOR MATERIAL:LCP ROHS
DWG. 製圖 ABBY	UNIT 單位 M M	SIZE. 紙張尺寸 A 4	PART NO. 料號 C0639-08DIBR00N
DATE 制表日 2016/07/19	PAGE 張數 1 OF 1	REV. 版次 A	